

Thermal Control of Power Electronics and Electric Machines

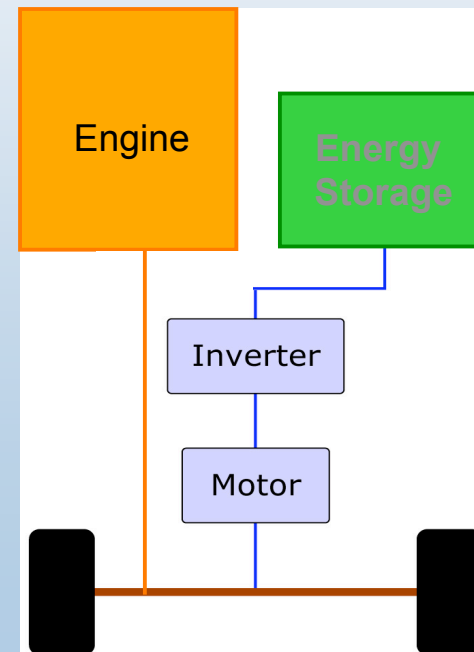
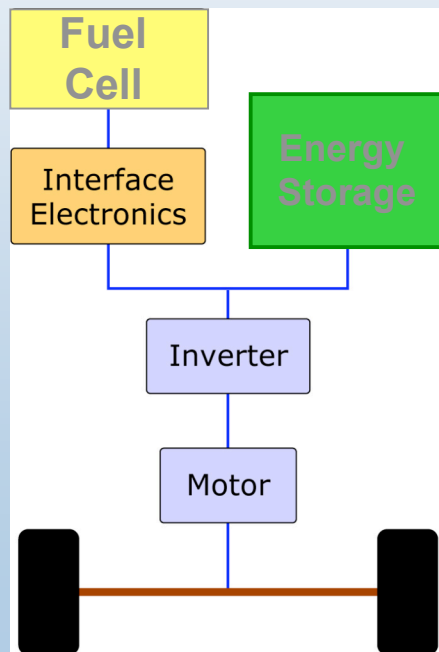
Vahab Hassani
National Renewable Energy Laboratory

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Why Thermal Control?

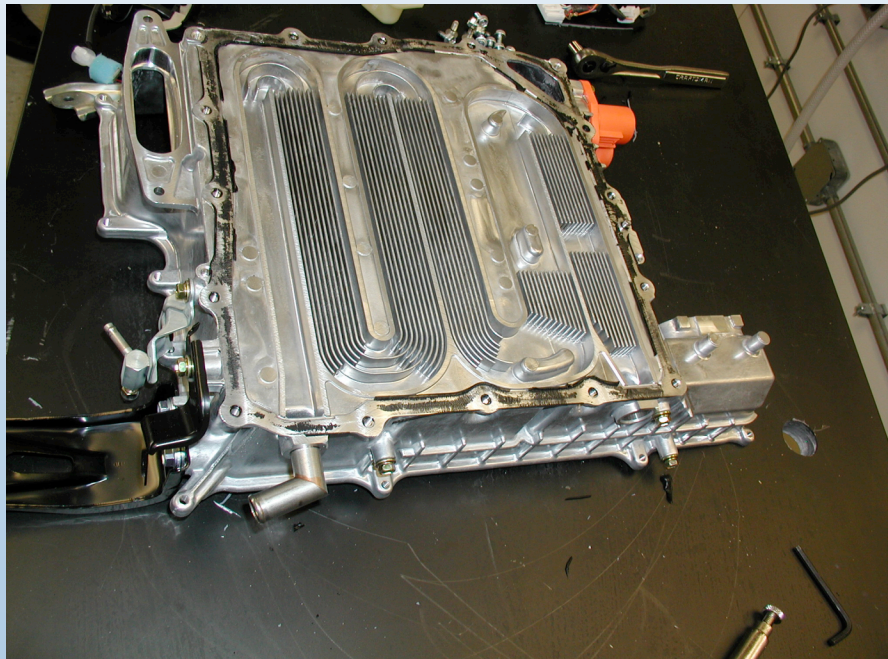
- Maintaining an acceptable operating temperature for power electronics and electric machine is crucial/electronics and motor will not function without thermal control
- Electronic demand in hybrid /fuel cell vehicles is increasing



Where Are We and Where We Would like to Go? (Current Status)

Current Status

- Current technology uses a separate cooling loop (70 °C coolant)
- Conventional single phase heat exchangers are used (fins of different shape)
- Heat fluxes are in the order of 60 W/cm²

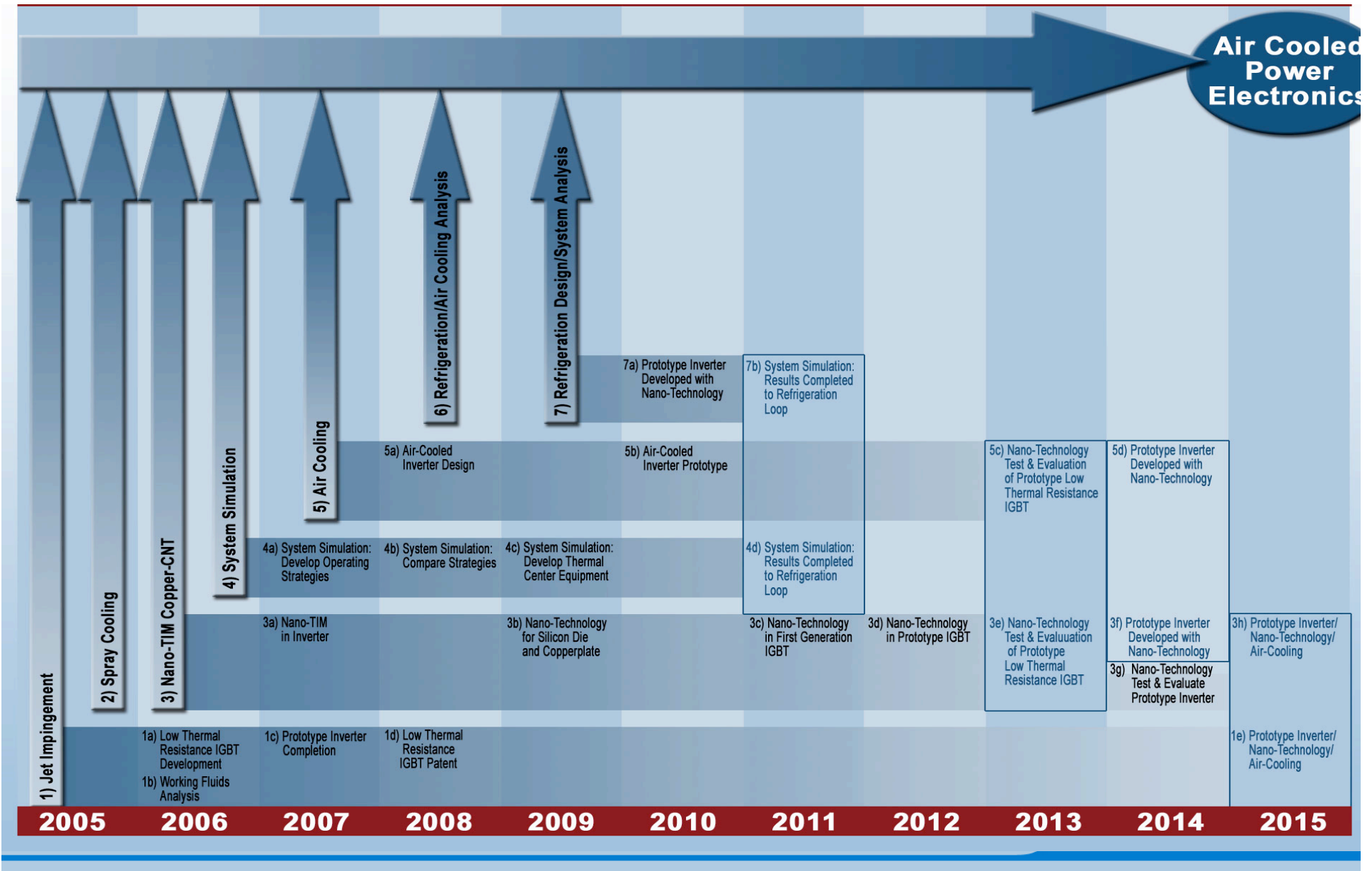


Where Are We and Where We Would like to Go? (Goals)

Goals

- Integrated cooling loop
- Inlet coolant at 105 °C for hybrid, 85 °C for FCV
- Heat fluxes at the order of up to 250 W/cm²
- Eventually, we would like to do air cooling by FY10 to FY15

Where Are We and Where We Would like to Go? (Goals)



Barriers

1. Volume and thermal control: bulky and difficult to package for automotive applications. Existing thermal management techniques are inadequate to dissipate high heat fluxes ($\sim 250 \text{ W/cm}^2$)
2. Cost: Material and processing technologies too costly for automotive industry, limitation requires operation at less than $125 \text{ }^\circ\text{C}$
3. Weight: Current components are too heavy and require additional structural support

Focus Areas and Purpose

Focus

- Power electronics cooling for both hybrid and FCVs under increased power levels.
- Evaluate/test/demonstrate component/system operation with coolant inlet temperature of 105 °C which imposes serious challenges on achieving reliability targets.
- System integration and achievement of component targets.

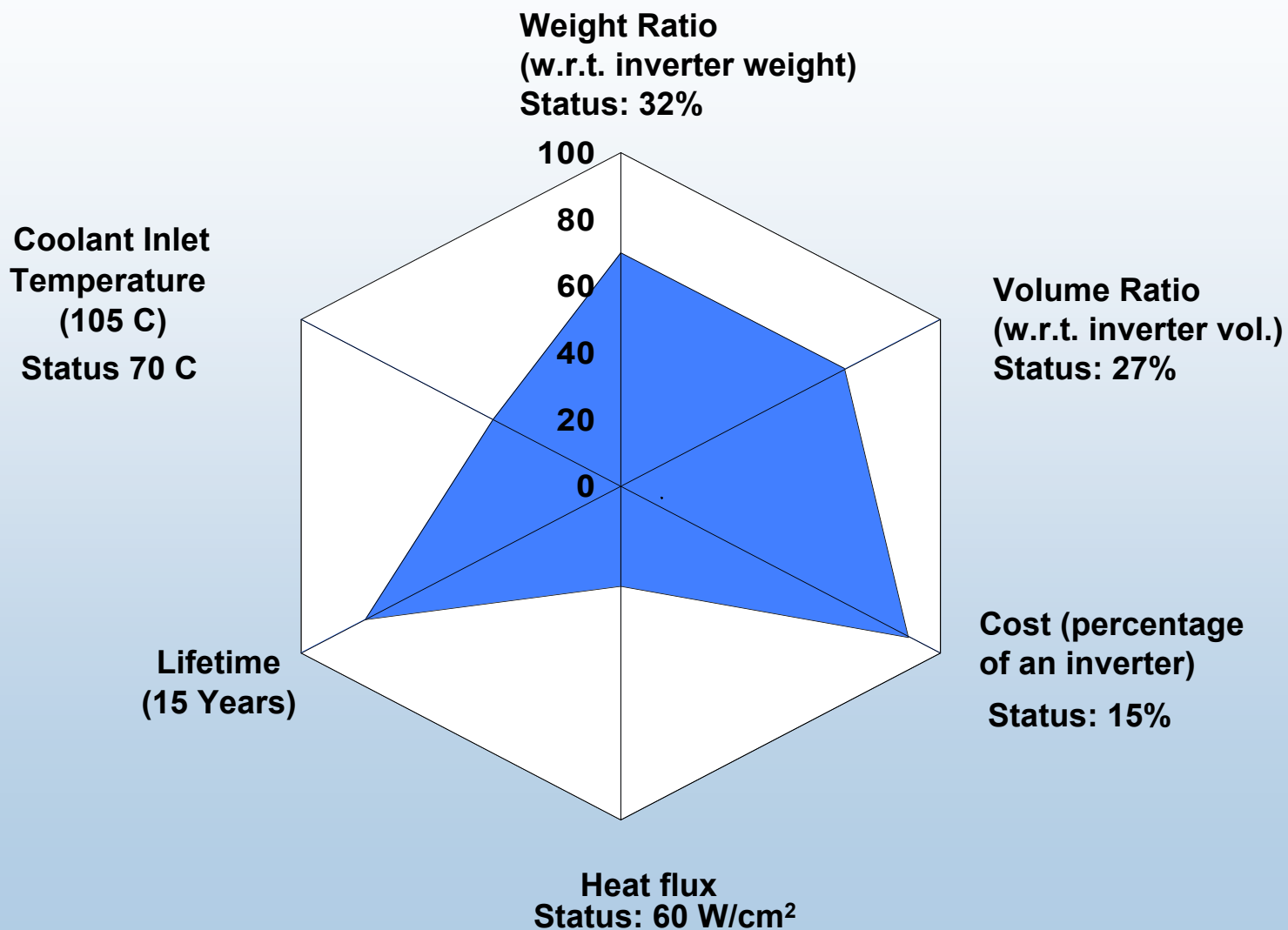
Purpose

- Reduce system cost, increasing reliability, specific power, power density, and efficiency

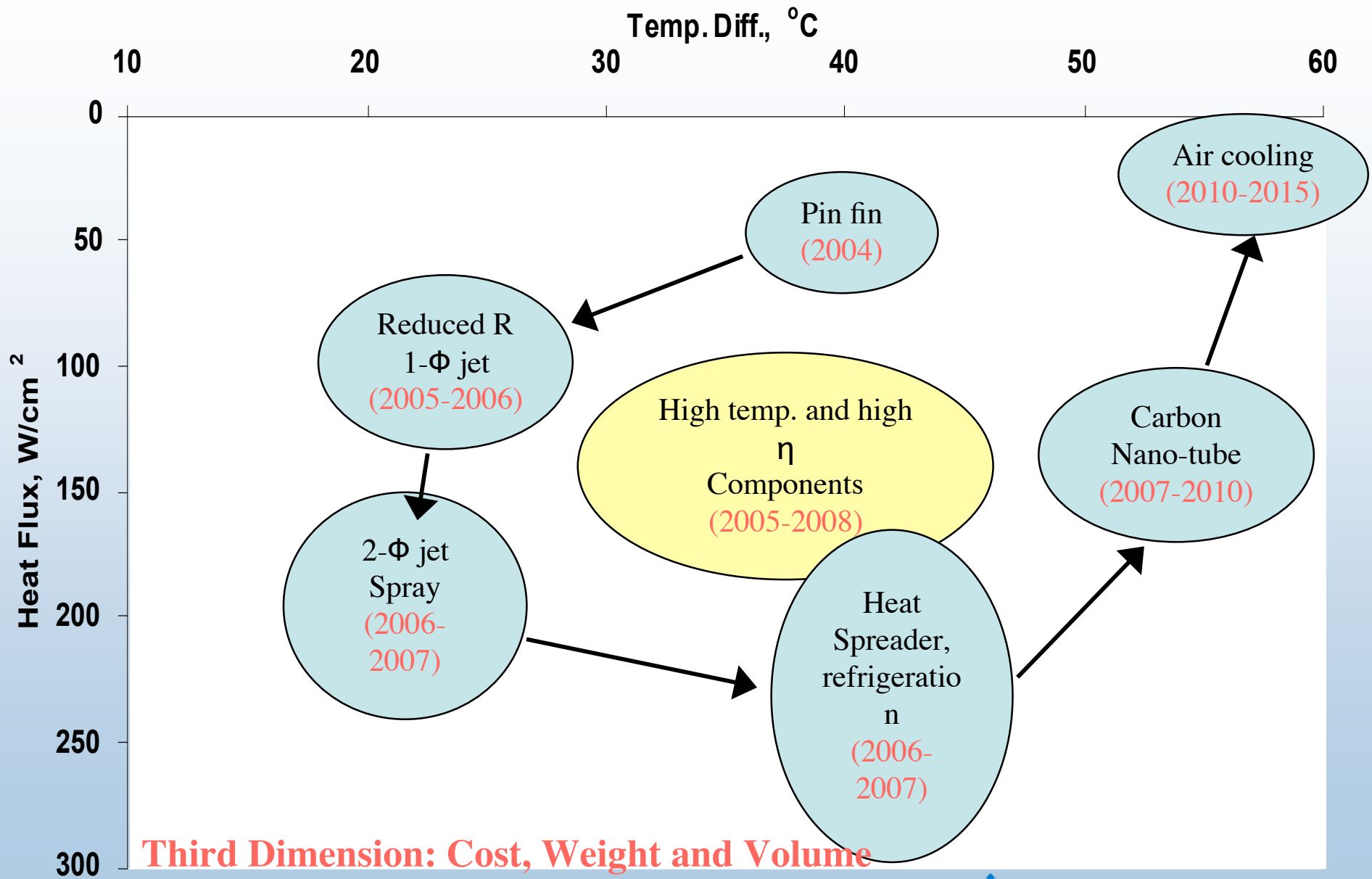
Thermal Control Near to Mid-Term Targets

$\Delta T(^{\circ}\text{C})$	20	30	40
q'' (W/cm ²)			
50	<ul style="list-style-type: none"> • 1-Φ jet 	<ul style="list-style-type: none"> • pin fin 	<ul style="list-style-type: none"> • pin fin • conv. fins
100	<ul style="list-style-type: none"> • 1-Φ jet • Spray 	<ul style="list-style-type: none"> • pin fin • 1-Φ jet 	<ul style="list-style-type: none"> • pin fin • heat spreader
150	<ul style="list-style-type: none"> • 1-Φ jet, high h • Spray 	<ul style="list-style-type: none"> • 1-Φ jet • Spray 	<ul style="list-style-type: none"> • 1-Φ jet • Spray
200	<ul style="list-style-type: none"> • 2-Φ jet • Spray • reduced R 	<ul style="list-style-type: none"> • 1-Φ jet, high h • Spray 	<ul style="list-style-type: none"> • 1-Φ jet • Spray • heat spreader
250	<ul style="list-style-type: none"> • 2-Φ jet • heat spreader • reduced R 	<ul style="list-style-type: none"> • 2-Φ jet • refrigeration • reduced R 	<ul style="list-style-type: none"> • 1-Φ jet, high h • Spray • refrigeration

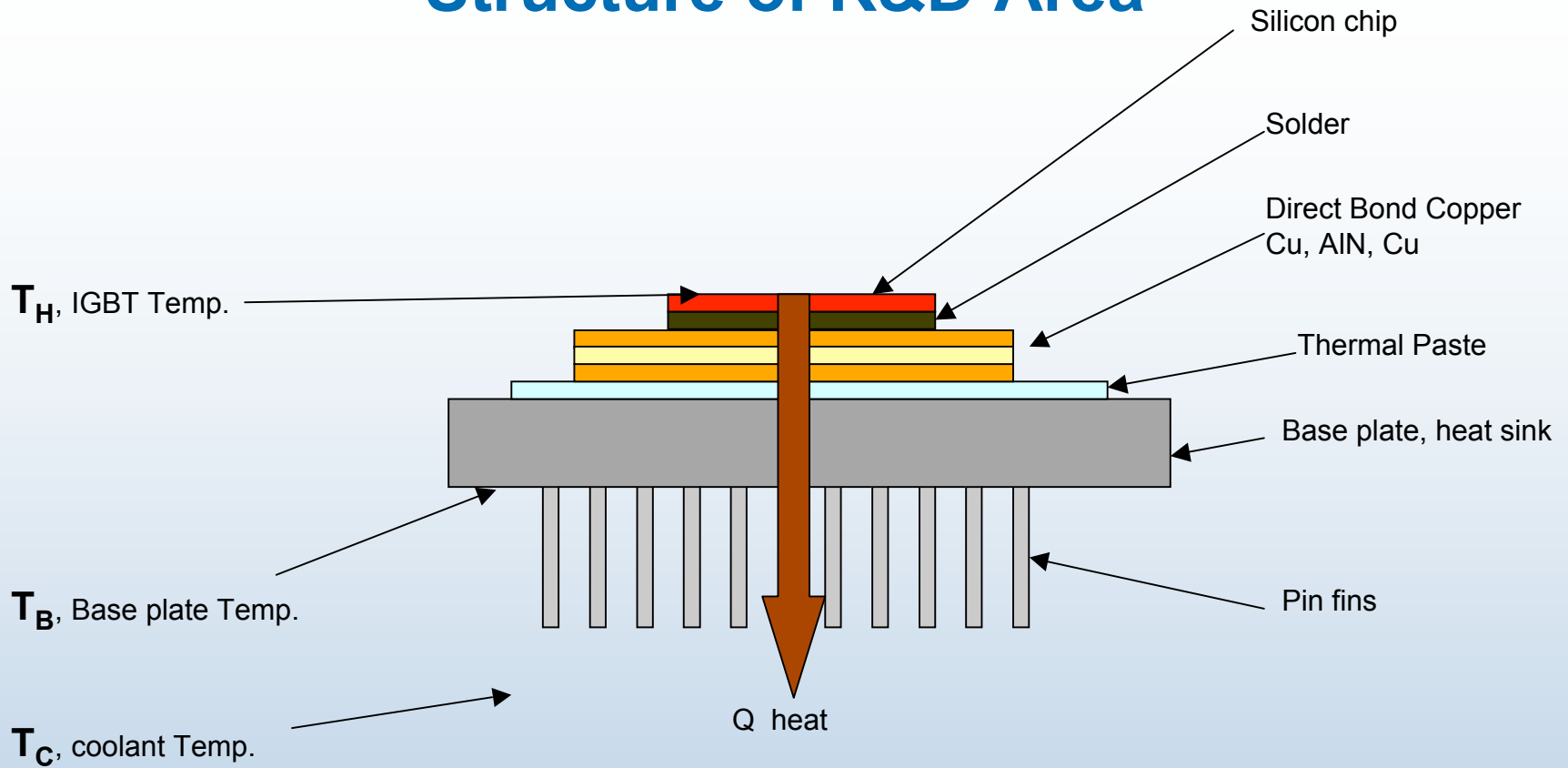
Thermal Control Target Spider Chart



Mid To Long Term Research Path



Structure of R&D Area



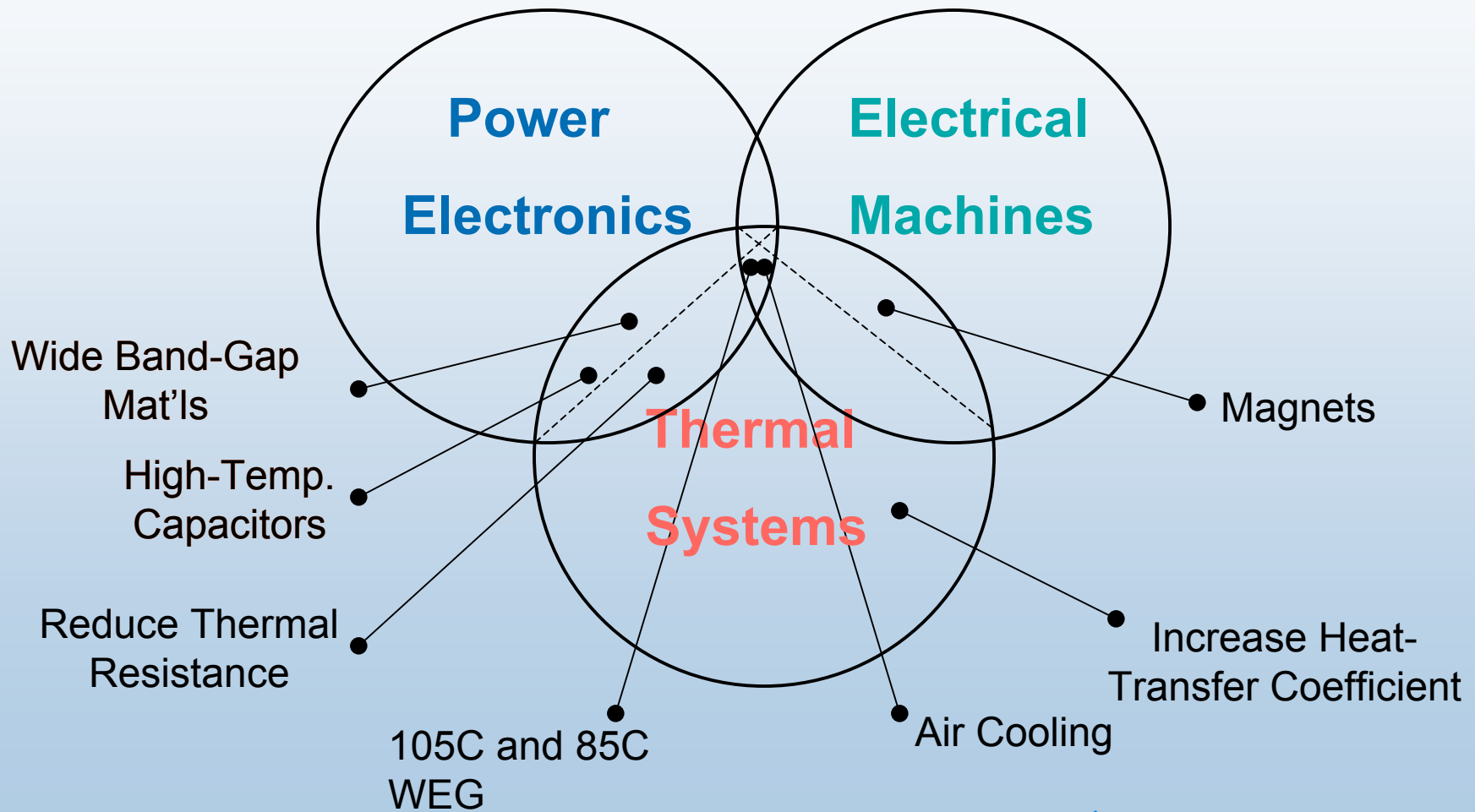
$$Q = \frac{(T_H - T_B)}{R_{solder} + R_{DBC} + R_{TIM}}$$

$$Q = h A (T_B - T_C)$$

Structure of R&D Area

- Increase fluid side heat transfer coefficient (spray cooling, jet impingement, take advantage of heat vaporization)
- Reduce overall thermal resistance (low thermal resistance IGBTs, heat spreaders, advanced highly conductive materials, carbon nano-tubes)
- Increase temperature difference (new materials that can operate at higher temperature, refrigeration)
- Reduce heat loss (high efficiency components)

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Projects for FY05

- Bench marking of competitive products
- Floating (Refrigeration) loop fabrication and results
- Inverter packaging
- Jet impingement modeling and testing
- Spray cooling modeling and generating critical heat flux curves for selected working fluids
- Development of User Defined Functions for two-phase modeling
- Analysis and testing of low thermal resistance IGBT structure

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Projects for FY06

- Bench marking of competitive products
- Floating (Refrigeration) loop fabrication and results
- Inverter packaging
- Jet impingement modeling and testing
- Spray cooling modeling and generating critical heat flux curves for selected working fluids
- Development of User Defined Functions for two-phase modeling
- Analysis and testing of low thermal resistance IGBT structure

Accomplishments

Jet impingement model/testing:

- NREL has completed modeling of single phase, single and multiple jet, free and submerged.
- NREL has completed modeling two-phase (boiling) jet impingement.

Spray cooling model/testing:

- NREL has developed a user friendly model to predict spray cooling heat transfer for various working fluids.
- ISR has completed application to an actual hardware; ORNL will be testing it in Jan. 2006.

Other Technologies:

- ORNL has completed the design of the refrigeration loop
- NREL has signed a CRADA with Semikron to build a prototype of low thermal resistance IGBT
- ORNL has completed Prius thermal control tests

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Presentations

- Benchmarking of competitive products
 - Floating loop fabrication and results
 - Inverter Packaging
 - Modeling High Heat Flux Heat Removal: Spray Cooling
 - Modeling High Heat Flux Heat Removal: Jet impingement
 - Low Thermal Resistance IGBT
 - Discussion
- John Hsu (ORNL)
Curt Ayers (ORNL)
John Hsu (ORNL)
- D. Bharathan (NREL)
- S. Narumanchi (NREL)
V. Hassani (NREL)
V. Hassani (NREL)

Where do we go from here?

1. Reduce thermal resistance:

- Develop high conductivity thermal grease
- a modeling tool for predicting heat transfer coefficients for jet impingement (single and two-phase, single and multiple jets)
- Low thermal resistance IGBT

2. Increase heat transfer coeff.:

- 2-phase
- Pulsating jets
- Develop Critical Heat Flux correlations for spray cooling with selected working fluids

3. Reduce sink Temp.

- Refrigeration
- Separate cooling loops

4. Increase die Temp.

- Use of SiC

5. Reduce heat loss

- High efficiency components

6. Eliminate liquid cooling loops

- Air cooling?